



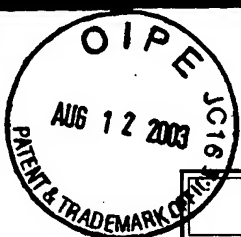
Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 45429
Application ID: 10054124
Title of Invention: SEMICONDUCTOR PACKAGE
INCLUDING LEADS WITH
VERTICALLY DOWNSET INNER
ENDS
First Named Inventor: JEFFREY MIKS
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-08-12
Effective Receipt Date: 2003-08-12
Submission Type: Information Disclosure
Statement
Filing Type:
Confirmation number: 6418
Attorney Docket Number: AMKOR003A
Total Fees Authorized: 180.0
Payment Category: Deposit Account
Deposit Account Number: 502304
Deposit Account Name: Mark B. Garred
Access Code: *****
RAM Payment Status: RAM success
RAM User ID: EFSPROD
RAM Accounting Date: 2003-08-12
RAM Sequence Number: 7




Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark
Office,ou=Department of Commerce,o=U.S. Government,c=US
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Electronic Version v18

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Title of Invention	SEMICONDUCTOR PACKAGE INCLUDING LEADS WITH VERTICALLY DOWNSET INNER ENDS																										
<p>Application Number: 10/054124 </p> <p>Confirmation Number: 6418</p> <p>First Named Applicant: JEFFREY MIKS</p> <p>Attorney Docket Number: AMKOR003A</p> <p>Art Unit: 2826</p> <p>Search string: (6258629).pn.</p> <p>US Patent Documents</p> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>6258629</td><td>2001-07-10</td><td>EULOGIA A. NIONES ET AL</td><td></td><td></td><td></td></tr></tbody></table> <p>Signature</p> <table border="1"><thead><tr><th>Examiner Name</th><th>Date</th></tr></thead><tbody><tr><td></td><td></td></tr></tbody></table>								init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	6258629	2001-07-10	EULOGIA A. NIONES ET AL				Examiner Name	Date		
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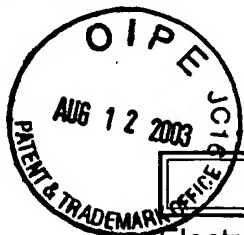
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Stylesheet Version v1.1.0

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<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>																
<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>MARK B GARRED Registered Number: 34823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	MARK B GARRED Registered Number: 34823	/mbg/	Attorney								
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us-fee-sheet	ids-usfees.xml															
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Comments

**FEE TRANSMITTAL**

Electronic Version v08
Stylesheet Version v08.0

Title of Invention	SEMICONDUCTOR PACKAGE INCLUDING LEADS WITH VERTICALLY DOWNSET INNER ENDS										
<p>Application Number: 10/054124 </p> <p>Date: 2003-08-12</p> <p>First Named Applicant: JEFFREY ALAN MIKS</p> <p>Attorney Docket Number: AMKOR003A</p> <p>Art Unit: 2826</p>											
<p>TOTAL FEE AUTHORIZED \$180</p> <p>Patent fees are subject to annual revisions on or about October 1st of each year.</p>											
BASIC FILING FEE											
<table border="1"><thead><tr><th>Fee Description</th><th>Fee Code</th><th>Amount \$</th><th>Fee Paid \$</th></tr></thead><tbody><tr><td>Submission Of Information Disclosure Stmt Fee</td><td>1806</td><td>180</td><td>180</td></tr></tbody></table>				Fee Description	Fee Code	Amount \$	Fee Paid \$	Submission Of Information Disclosure Stmt Fee	1806	180	180
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Submission Of Information Disclosure Stmt Fee	1806	180	180								
<p>AUTHORIZED BILLING INFORMATION</p> <p>The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:</p> <p>Deposit account number: 502304</p> <p>Access Code: ****</p> <p>Deposit name: Stetina Brunda Garred Brucker</p> <p>Deposit authorized name: Mark B. Garred</p> <p>Signature: /mbg/</p> <p>Date (YYYYMMDD): 2003-08-12</p>											

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